

Features

- Very high speed: 45 ns
- Temperature ranges
 - Industrial: -40 °C to +85 °C
- Wide voltage range: 2.20 V to 3.60 V and 4.5 V to 5.5 V
- Ultra low standby power
 - Typical standby current: 3.5 μA
 - Maximum standby current: 8.7 μA
- Ultra low active power
 - Typical active current: 3.5 mA at f = 1 MHz
- Automatic power down when deselected
- Complementary metal oxide semiconductor (CMOS) for optimum speed and power
- Available in a 44-pin TSOP II and 48-ball VFBGA Packages

Functional Description

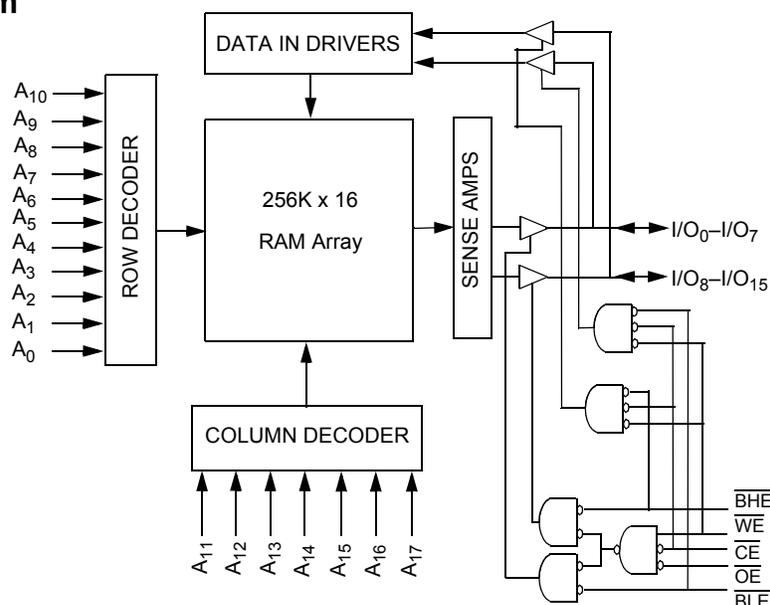
The CY62146GN is a high performance CMOS static RAM organized as 256K words by 16 bits. This device features an advanced circuit design designed to provide an ultra low active current. Ultra low active current is ideal for providing More Battery Life™ (MoBL®) in portable applications such as cellular

telephones. The device also has an automatic power down feature that significantly reduces power consumption by 80 percent when addresses are not toggling. The device can also be put into standby mode reducing power consumption by more than 99 percent when deselected (CE HIGH). The input and output pins (I/O₀ through I/O₁₅) are placed in a high impedance state when the device is deselected (CE HIGH), outputs are disabled (OE HIGH), both Byte High Enable and Byte Low Enable are disabled (BHE, BLE HIGH), or a write operation is in progress (CE LOW and WE LOW).

To write to the device, take Chip Enable (\overline{CE}) and Write Enable (\overline{WE}) input LOW. If Byte Low Enable (BLE) is LOW, then data from I/O pins (I/O₀ through I/O₇) is written into the location specified on the address pins (A₀ through A₁₇). If Byte High Enable (BHE) is LOW, then data from the I/O pins (I/O₈ through I/O₁₅) is written into the location specified on the address pins (A₀ through A₁₇).

To read from the device, take Chip Enable (\overline{CE}) and Output Enable (\overline{OE}) LOW while forcing the Write Enable (\overline{WE}) HIGH. If Byte Low Enable (BLE) is LOW, then data from the memory location specified by the address pins appears on I/O₀ to I/O₇. If Byte High Enable (BHE) is LOW, then data from memory appears on I/O₈ to I/O₁₅. See the Truth Table on page 11 for a complete description of read and write modes.

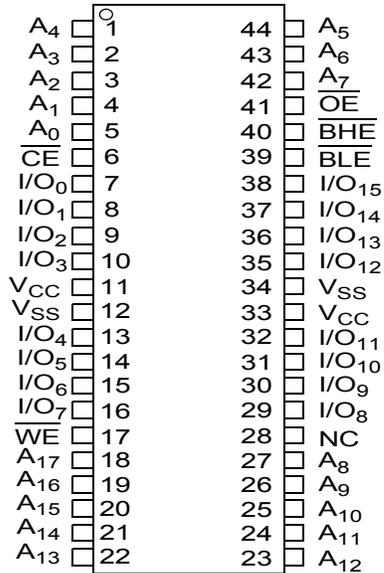
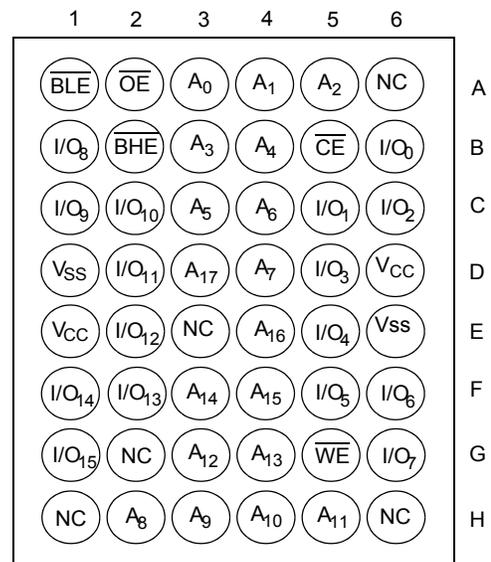
Logic Block Diagram



Contents

Pin Configurations	3	Ordering Information	12
Product Portfolio	3	Ordering Code Definitions	12
Maximum Ratings	4	Package Diagrams	13
Operating Range	4	Acronyms	15
Electrical Characteristics	4	Document Conventions	15
Capacitance	5	Units of Measure	15
Thermal Resistance	5	Document History Page	16
AC Test Loads and Waveforms	5	Sales, Solutions, and Legal Information	17
Data Retention Characteristics	6	Worldwide Sales and Design Support	17
Data Retention Waveform	6	Products	17
Switching Characteristics	7	PSoC® Solutions	17
Switching Waveforms	8	Cypress Developer Community	17
Truth Table	11	Technical Support	17

Pin Configurations

Figure 1. 44-pin TSOP II pinout ^[1]

Figure 2. 48-ball VFBGA pinout ^[1]


Product Portfolio

Product	Range	V _{CC} Range (V)			Speed (ns)	Power Dissipation					
						Operating I _{CC} (mA)				Standby I _{SB2} (μA)	
		f = 1 MHz		f = f _{max}							
		Min	Typ ^[2]	Max		Typ ^[2]	Max	Typ ^[2]	Max	Typ ^[2]	Max
CY62146GN30	Industrial	2.2	3.0	3.6	45	3.5	6	15	20	3.5	8.7
CY62146GN		4.5	5.0	5.5							

Notes

- NC pins are not connected on the die.
- Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC(typ)}, T_A = 25 °C.

Maximum Ratings

Exceeding the maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Storage temperature	-65 °C to + 150 °C
Ambient temperature with power applied	-55 °C to + 125 °C
Supply voltage to ground potential	-0.3 V to + V _{CC} + 0.5 V
DC voltage applied to outputs in High-Z state ^[3, 4]	-0.3 V to + V _{CC} + 0.5 V

DC input voltage ^[3, 4]	-0.3 V to + V _{CC} + 0.5 V
Output current into outputs (LOW)	20 mA
Static Discharge Voltage (per MIL-STD-883, Method 3015)	>2001 V
Latch-up Current	>200 mA

Operating Range

Device	Range	Ambient Temperature	V _{CC} ^[5]
CY62146GN30	Industrial	-40 °C to +85 °C	2.2 V to 3.6 V, 4.5 V to 5.5 V

Electrical Characteristics

Over the Operating Range

Parameter	Description	Test Conditions	45 ns			Unit	
			Min	Typ ^[6]	Max		
V _{OH}	Output high voltage	2.2 V to 2.7 V	V _{CC} = Min, I _{OH} = -0.1 mA	2	-	-	V
		2.7 V to 3.6 V	V _{CC} = Min, I _{OH} = -1.0 mA	2.2	-	-	
		4.5 V to 5.5 V	V _{CC} = Min, I _{OH} = -1.0 mA	2.4	-	-	
		4.5 V to 5.5 V	V _{CC} = Min, I _{OH} = -0.1 mA	V _{CC} - 0.5 ^[7]	-	-	
V _{OL}	Output low voltage	2.2 V to 2.7 V	V _{CC} = Min, I _{OL} = 0.1 mA	-	-	0.4	V
		2.7 V to 3.6 V	V _{CC} = Min, I _{OL} = 2.1 mA	-	-	0.4	
		4.5 V to 5.5 V	V _{CC} = Min, I _{OL} = 2.1 mA	-	-	0.4	
V _{IH} ^[4]	Input high voltage	2.2 V to 2.7 V	-	2.0	-	V _{CC} + 0.3	V
		2.7 V to 3.6 V	-	2.0	-	V _{CC} + 0.3	
		4.5 V to 5.5 V	-	2.2	-	V _{CC} + 0.5	
V _{IL} ^[3]	Input LOW Voltage	2.2 V to 2.7 V	V _{CC} = 2.2 V to 2.7 V	-0.3	-	0.6	V
		2.7 V to 3.6 V	V _{CC} = 2.7 V to 3.6 V	-0.3	-	0.8	
		4.5 V to 5.5 V	-	-0.5	-	0.8	
I _{IX}	Input leakage current	GND ≤ V _I ≤ V _{CC}	-1	-	+1	mA	
I _{OZ}	Output leakage current	GND ≤ V _O ≤ V _{CC} , Output disabled	-1	-	+1	mA	
I _{CC}	V _{CC} operating supply current	f = f _{max} = 1/t _{RC}	V _{CC} = V _{CC(max)} , I _{OUT} = 0 mA	-	15	20	mA
		f = 1 MHz	CMOS levels	-	3.5	6	
I _{SB1}	Automatic CE power down current – CMOS inputs	$\overline{CE} > V_{CC} - 0.2 V$, $V_{IN} > V_{CC} - 0.2 V$ or $V_{IN} < 0.2 V$, $f = f_{max}$ (Address and data only), $f = 0$ (\overline{OE} , \overline{BHE} , \overline{BLE} and \overline{WE}), $V_{CC} = 3.60 V$	-	3.5	8.7	μA	
I _{SB2} ^[8]	Automatic CE power down current – CMOS inputs	$\overline{CE} \geq V_{CC} - 0.2 V$, $V_{IN} \geq V_{CC} - 0.2 V$ or $V_{IN} \leq 0.2 V$, $f = 0$, V _{CC} = 3.60 V	-	3.5	8.7	μA	

Notes

- V_{IL(min)} = -2.0 V for pulse durations less than 2 ns.
- V_{IH(max)} = V_{CC} + 2.0 V for pulse durations less than 2 ns.
- Full-device operation requires linear V_{CC} ramp from V_{DR} to V_{CC(min)} > 100 μs or stable at V_{CC(min)} > 100 μs.
- Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC(typ)}, T_A = 25 °C.
- This parameter is guaranteed by design and not tested.
- Chip enable (CE) need to be tied to CMOS levels to meet the I_{SB1} / I_{SB2} / I_{CCDR} spec. Other inputs can be left floating.

Capacitance

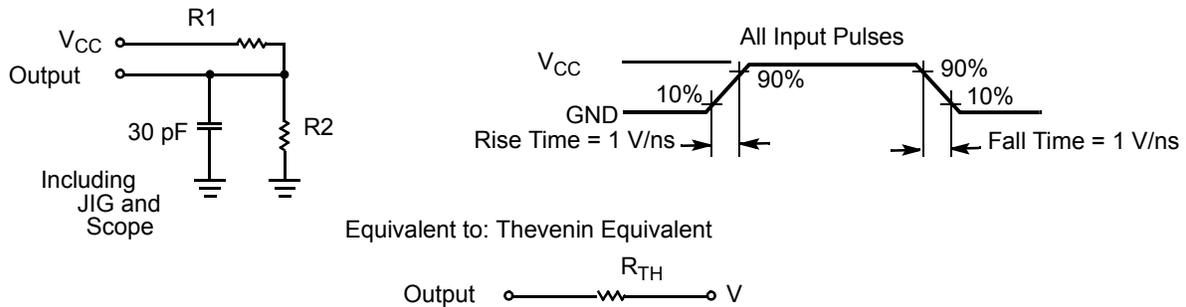
Parameter ^[9]	Description	Test Conditions	Max	Unit
C _{IN}	Input capacitance	T _A = 25 °C, f = 1 MHz, V _{CC} = V _{CC(typ)}	10	pF
C _{OUT}	Output capacitance		10	pF

Thermal Resistance

Parameter ^[9]	Description	Test Conditions	TSOP II	Unit
Θ _{JA}	Thermal resistance (junction to ambient)	Still air, soldered on a 3 × 4.5 inch, four-layer printed circuit board	68.85	°C/W
Θ _{JC}	Thermal resistance (junction to case)		15.97	°C/W

AC Test Loads and Waveforms

Figure 3. AC Test Loads and Waveforms^[10]



Parameters	2.50 V	3.0 V	Unit
R1	16667	1103	Ω
R2	15385	1554	Ω
R _{TH}	8000	645	Ω
V _{TH}	1.20	1.75	V

Note

- 9. Tested initially and after any design or process changes that may affect these parameters.
- 10. Full-device operation requires linear V_{CC} ramp from V_{DR} to V_{CC(min)} ≥ 100 μs or stable at V_{CC(min)} ≥ 100 μs.

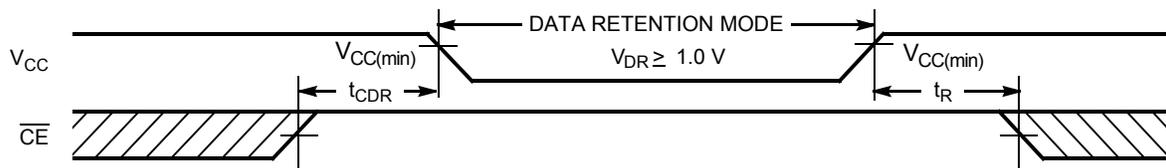
Data Retention Characteristics

Over the Operating Range

Parameter	Description	Conditions	Min	Typ	Max	Unit
V_{DR}	V_{CC} for data retention		1.0	–	–	V
$I_{CCDR}^{[11, 12]}$	Data retention current	$V_{CC} = 1.2\text{ V}$, $\overline{CE} \geq V_{CC} - 0.2\text{ V}$, $V_{IN} \geq V_{CC} - 0.2\text{ V}$ or $V_{IN} \leq 0.2\text{ V}$	–	–	13	μA
$t_{CDR}^{[13]}$	Chip deselect to data retention time	–	0	–	–	ns
$t_R^{[14]}$	Operation recovery time	–	45	–	–	ns

Data Retention Waveform

Figure 4. Data Retention Waveform



Notes

11. Chip enable (CE) needs to be tied to CMOS levels to meet the I_{SB1} / I_{SB2} / I_{CCDR} spec. Other inputs can be left floating.
12. I_{CCDR} is guaranteed only after device is first powered up to $V_{CC(min)}$ and then brought down to V_{DR} .
13. Tested initially and after any design or process changes that may affect these parameters.
14. Full-device operation requires linear V_{CC} ramp from V_{DR} to $V_{CC(min)}$ > 100 μs or stable at $V_{CC(min)}$ > 100 μs .

Switching Characteristics

Over the Operating Range

Parameter ^[15, 16]	Description	45 ns		Unit
		Min	Max	
Read Cycle				
t_{RC}	Read cycle time	45	–	ns
t_{AA}	Address to data valid	–	45	ns
t_{OHA}	Data hold from address change	10	–	ns
t_{ACE}	\overline{CE} LOW to data valid	–	45	ns
t_{DOE}	\overline{OE} LOW to data valid	–	22	ns
t_{LZOE}	\overline{OE} LOW to Low-Z ^[17]	5	–	ns
t_{HZOE}	\overline{OE} HIGH to High-Z ^[17, 18]	–	18	ns
t_{LZCE}	\overline{CE} LOW to Low-Z ^[17]	10	–	ns
t_{HZCE}	\overline{CE} HIGH to High-Z ^[17, 18]	–	18	ns
t_{PU}	\overline{CE} LOW to power up	0	–	ns
t_{PD}	\overline{CE} HIGH to power down	–	45	ns
t_{DBE}	$\overline{BLE} / \overline{BHE}$ LOW to data valid	–	22	ns
t_{LZBE}	$\overline{BLE} / \overline{BHE}$ LOW to Low-Z ^[17]	5	–	ns
t_{HZBE}	$\overline{BLE} / \overline{BHE}$ HIGH to High-Z ^[17, 18]	–	18	ns
Write Cycle ^[19, 20]				
t_{WC}	Write cycle time	45	–	ns
t_{SCE}	\overline{CE} LOW to write end	35	–	ns
t_{AW}	Address setup to write end	35	–	ns
t_{HA}	Address hold from write end	0	–	ns
t_{SA}	Address setup to write start	0	–	ns
t_{PWE}	\overline{WE} pulse width	35	–	ns
t_{BW}	$\overline{BLE} / \overline{BHE}$ LOW to write end	35	–	ns
t_{SD}	Data setup to write end	25	–	ns
t_{HD}	Data hold from write end	0	–	ns
t_{HZWE}	\overline{WE} LOW to High-Z ^[17, 18]	–	18	ns
t_{LZWE}	\overline{WE} HIGH to Low-Z ^[17]	10	–	ns

Notes

15. Test conditions for all parameters other than tri-state parameters assume signal transition time of 3 ns (1 V/ns) or less, timing reference levels of $V_{CC(typ)}/2$, input pulse levels of 0 to $V_{CC(typ)}$, and output loading of the specified I_{OL}/I_{OH} as shown in the [Figure 3 on page 5](#).
16. These parameters are guaranteed by design.
17. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , t_{HZBE} is less than t_{LZBE} , t_{HZOE} is less than t_{LZOE} , and t_{HZWE} is less than t_{LZWE} for any given device.
18. t_{HZOE} , t_{HZCE} , t_{HZBE} , and t_{HZWE} transitions are measured when the outputs enter a high impedance state.
19. The internal write time of the memory is defined by the overlap of \overline{WE} , $\overline{CE} = V_{IL}$, \overline{BHE} and/or $\overline{BLE} = V_{IL}$. All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must be referenced to the edge of the signal that terminates the write.
20. The minimum write pulse width for Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW) should be sum of t_{HZWE} and t_{SD} .

Switching Waveforms

Figure 5. Read Cycle 1 (Address Transition Controlled) [21, 22]

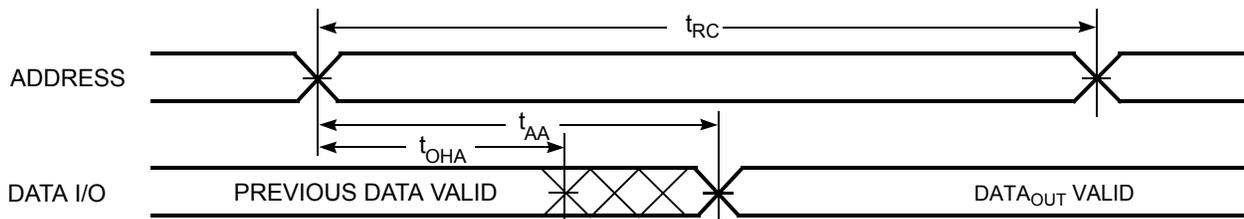
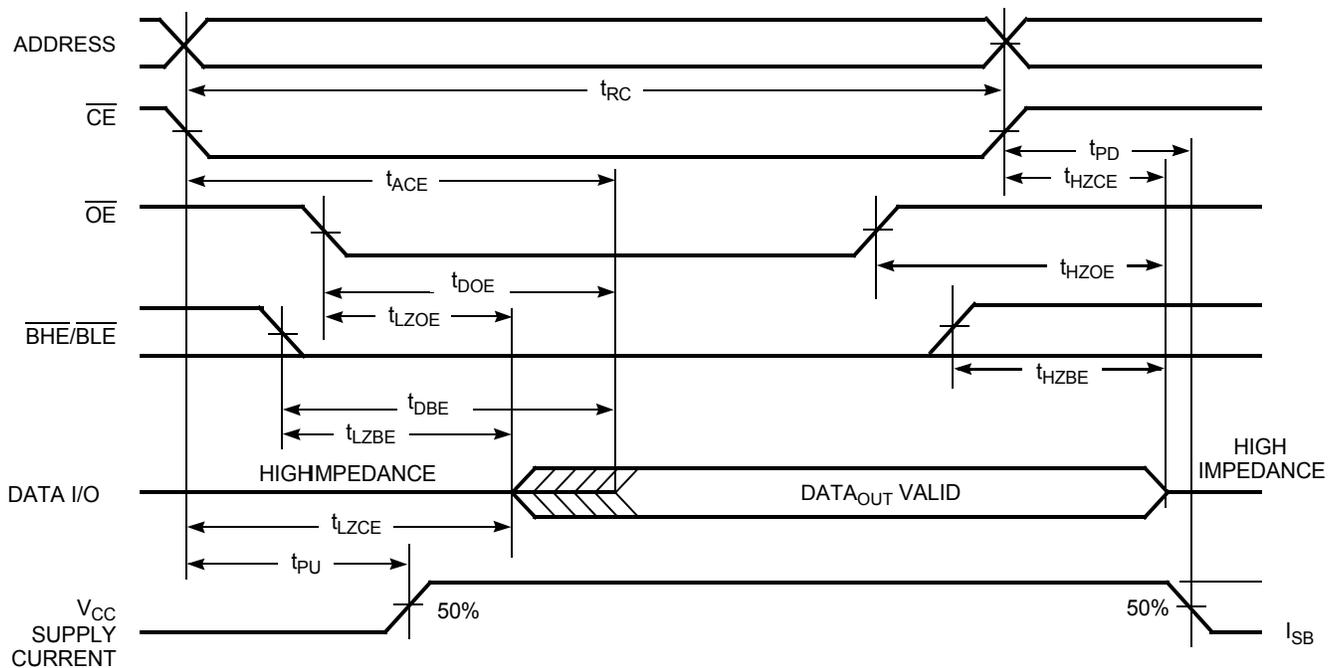


Figure 6. Read Cycle No. 2 (\overline{OE} Controlled) [22, 23]



Notes

21. The device is continuously selected. \overline{OE} , $\overline{CE} = V_{IL}$, \overline{BHE} and/or $\overline{BLE} = V_{IL}$.
22. \overline{WE} is HIGH for read cycle.
23. Address valid before or similar to \overline{CE} .

Switching Waveforms (continued)

Figure 7. Write Cycle No. 1 ($\overline{\text{WE}}$ Controlled) [24, 25, 26]

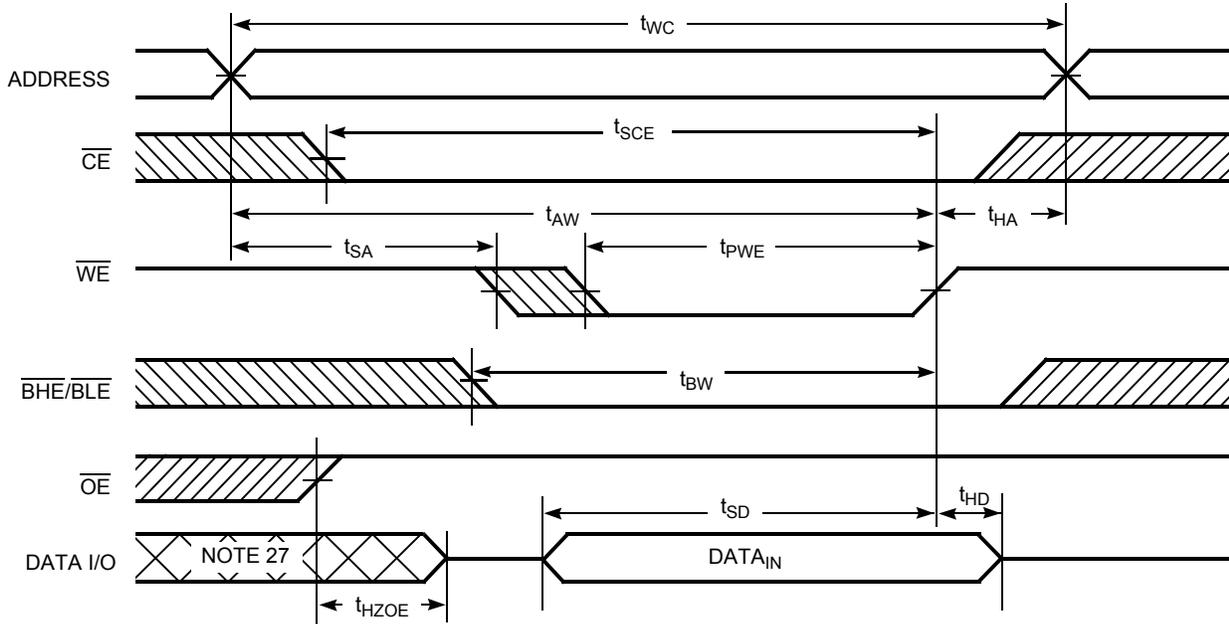
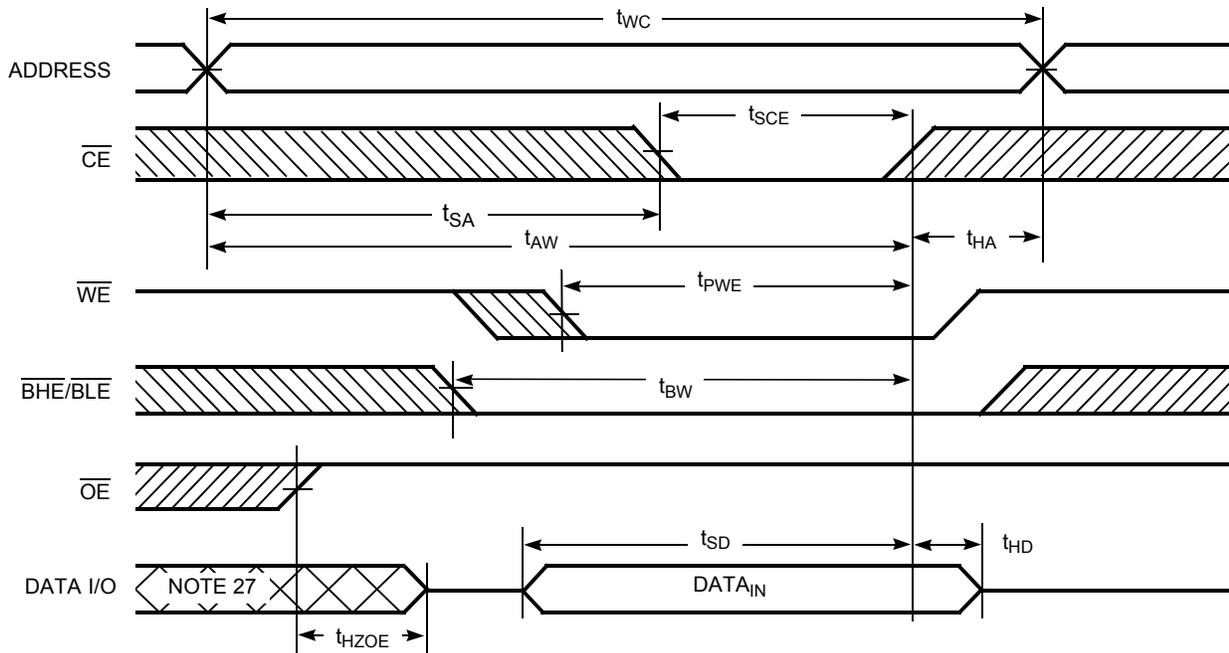


Figure 8. Write Cycle No. 2 ($\overline{\text{CE}}$ Controlled) [24, 25, 26]



Notes

- 24. The internal write time of the memory is defined by the overlap of $\overline{\text{WE}}$, $\overline{\text{CE}} = V_{\text{IL}}$, $\overline{\text{BHE}}$ and/or $\overline{\text{BLE}} = V_{\text{IL}}$. All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must be referenced to the edge of the signal that terminates the write.
- 25. Data I/O is high impedance if $\overline{\text{OE}} = V_{\text{IH}}$.
- 26. If $\overline{\text{CE}}$ goes HIGH simultaneously with $\overline{\text{WE}} = V_{\text{IH}}$, the output remains in a high impedance state.
- 27. During this period, the I/Os are in output state and input signals must not be applied.

Switching Waveforms (continued)

Figure 9. Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW) [28, 29]

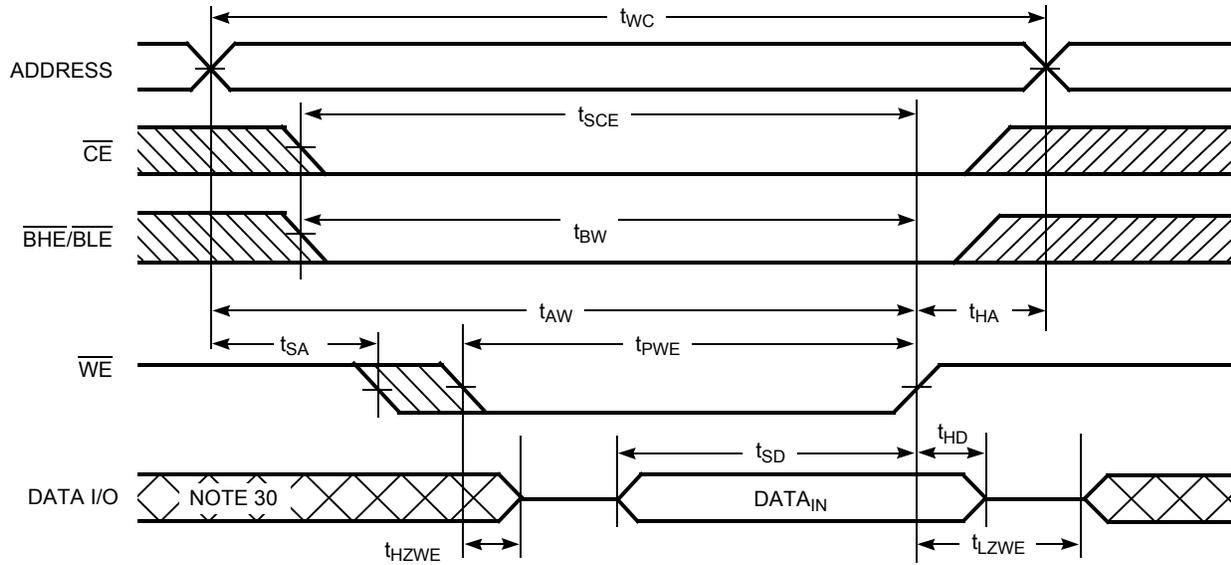
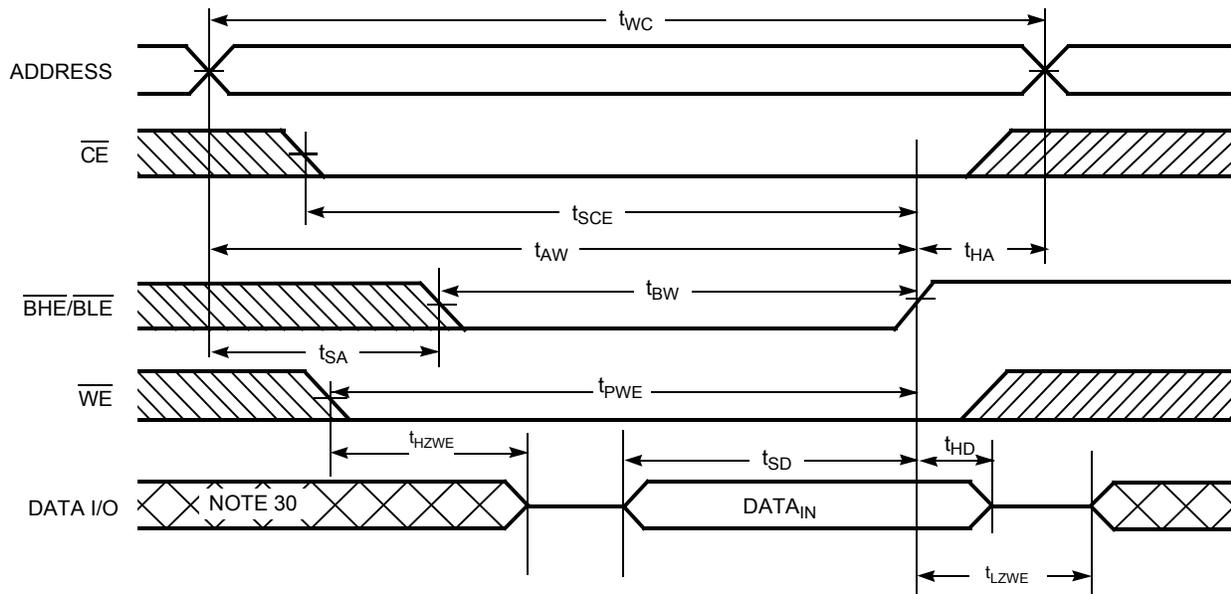


Figure 10. Write Cycle No. 4 ($\overline{BHE}/\overline{BLE}$ Controlled, \overline{OE} LOW) [28]



Notes

28. If \overline{CE} goes HIGH simultaneously with $\overline{WE} = V_{IH}$, the output remains in a high impedance state.

29. The minimum write pulse width for Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW) should be sum of t_{HZWE} and t_{SD} .

30. During this period, the I/Os are in output state and input signals must not be applied.

Truth Table

CE ^[31]	WE	OE	BHE	BLE	Inputs/Outputs	Mode	Power
H	X	X	X	X	High-Z	Deselect/power-down	Standby (I _{SB})
L	X	X	H	H	High-Z	Output disabled	Active (I _{CC})
L	H	L	L	L	Data out (I/O ₀ –I/O ₁₅)	Read	Active (I _{CC})
L	H	L	H	L	Data out (I/O ₀ –I/O ₇); I/O ₈ –I/O ₁₅ in High-Z	Read	Active (I _{CC})
L	H	L	L	H	Data out (I/O ₈ –I/O ₁₅); I/O ₀ –I/O ₇ in High-Z	Read	Active (I _{CC})
L	H	H	X	X	High-Z	Output disabled	Active (I _{CC})
L	L	X	L	L	Data in (I/O ₀ –I/O ₁₅)	Write	Active (I _{CC})
L	L	X	H	L	Data in (I/O ₀ –I/O ₇); I/O ₈ –I/O ₁₅ in High-Z	Write	Active (I _{CC})
L	L	X	L	H	Data in (I/O ₈ –I/O ₁₅); I/O ₀ –I/O ₇ in High-Z	Write	Active (I _{CC})

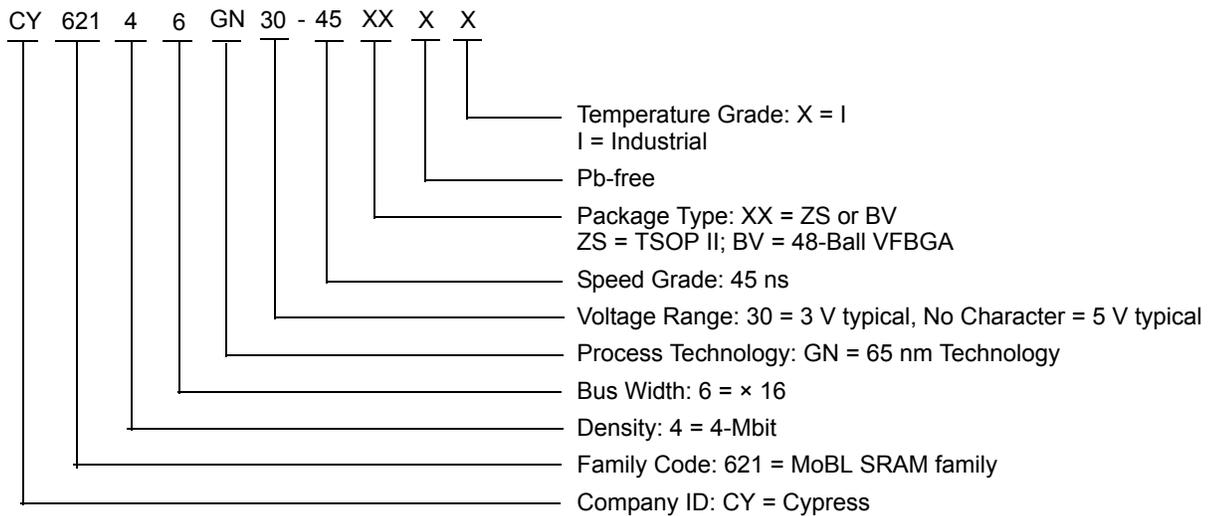
Note

31. Chip enable must be at CMOS levels (not floating). Intermediate voltage levels on this pin is not permitted.

Ordering Information

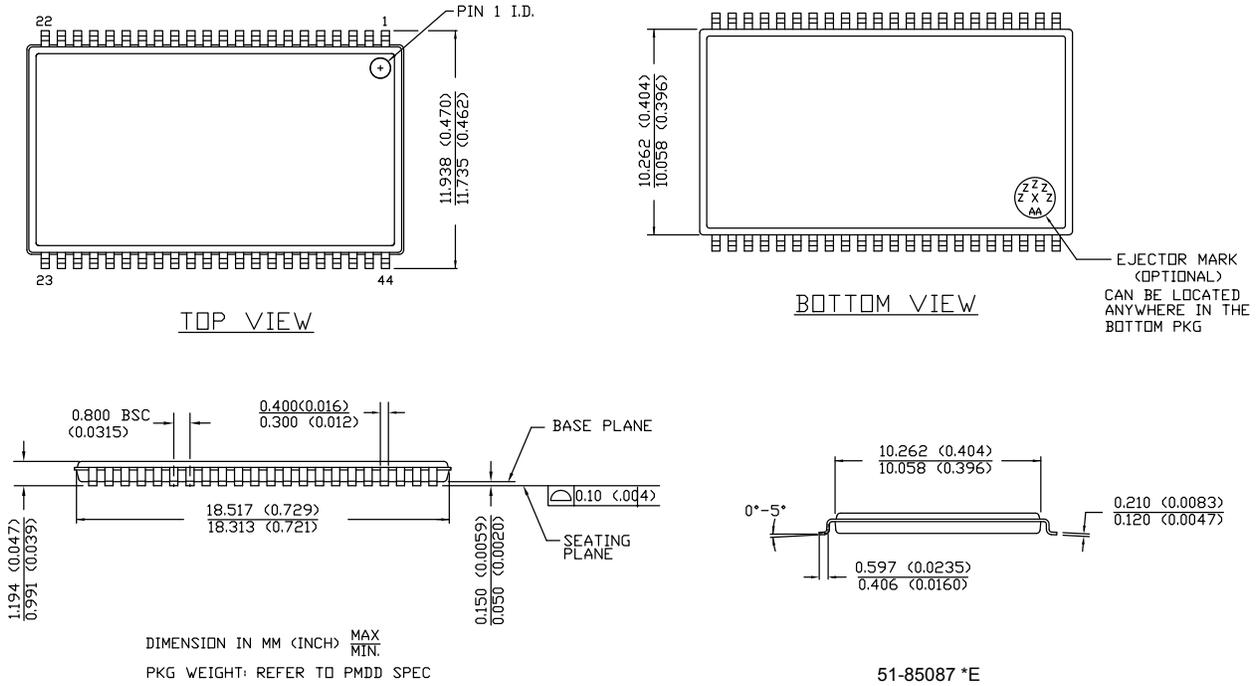
Speed (ns)	Voltage Range (V)	Ordering Code	Package Diagram	Package Type	Operating Range
45	2.2 V–3.6 V	CY62146GN30-45ZSXI	51-85087	44-pin TSOP II (Pb-free)	Industrial
		CY62146GN30-45BVXI	51-85150	48-ball VFBGA (6 × 8 × 1 mm) (Pb-free)	
	4.5 V–5.5 V	CY62146GN-45ZSXI	51-85087	44-pin TSOP II (Pb-free)	

Ordering Code Definitions



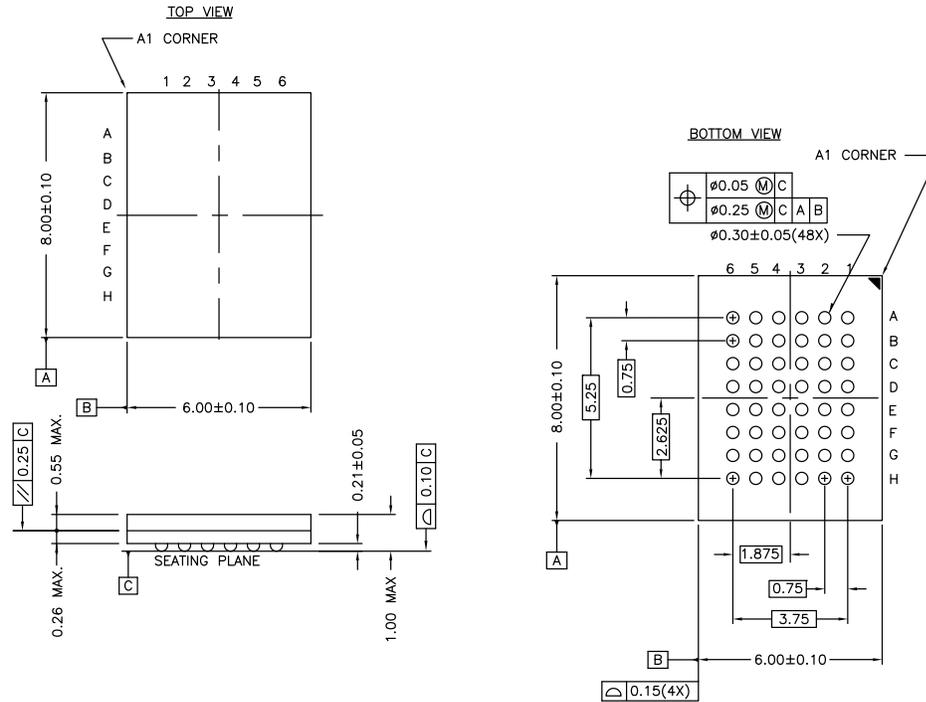
Package Diagrams

Figure 11. 44-pin TSOP Z44-II Package Outline, 51-85087



Package Diagrams (continued)

Figure 12. 48-ball VFBGA (6 × 8 × 1.0 mm) BV48/BZ48 Package Outline, 51-85150



NOTE:
 PACKAGE WEIGHT: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress web.

51-85150 *H

Acronyms

Acronym	Description
$\overline{\text{BHE}}$	byte high enable
$\overline{\text{BLE}}$	byte low enable
CMOS	complementary metal oxide semiconductor
$\overline{\text{CE}}$	chip enable
I/O	input/output
$\overline{\text{OE}}$	output enable
SRAM	static random access memory
TSOP	thin small outline package
VFBGA	very fine-pitch ball grid array
$\overline{\text{WE}}$	write enable

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	Degrees Celsius
MHz	megahertz
μA	microamperes
mA	milliamperes
ns	nanoseconds
Ω	ohms
pF	picofarads
V	volts
W	watts

Document History Page

Document Title: CY62146GN MoBL [®] , 4-Mbit (256K × 16) Static RAM Document Number: 001-95417				
Rev.	ECN No.	Orig. of Change	Submission Date	Description of Change
**	5048897	NILE	12/14/2015	New data sheet.
*A	5072822	NILE	01/05/2016	Added "4.5 V to 5.5 V" voltage range related information in all instances across the document. Updated Ordering Information : Updated part numbers.
*B	5092237	NILE	01/21/2016	Added 48-ball VFPGA package related information in all instances across the document. Updated Ordering Information : Updated part numbers. Updated Package Diagrams : Added spec 51-85150 *H (Figure 12).
*C	5142534	NILE	02/18/2016	Updated Ordering Code Definitions under Ordering Information (Replaced "GN = 90 nm" with "GN = 65 nm Technology"). Updated to new template.

Sales, Solutions, and Legal Information

Worldwide Sales and Design Support

Cypress maintains a worldwide network of offices, solution centers, manufacturer's representatives, and distributors. To find the office closest to you, visit us at [Cypress Locations](#).

Products

ARM [®] Cortex [®] Microcontrollers	cypress.com/arm
Automotive	cypress.com/automotive
Clocks & Buffers	cypress.com/clocks
Interface	cypress.com/interface
Lighting & Power Control	cypress.com/powerpsoc
Memory	cypress.com/memory
PSoC	cypress.com/psoc
Touch Sensing	cypress.com/touch
USB Controllers	cypress.com/usb
Wireless/RF	cypress.com/wireless

PSoC[®] Solutions

cypress.com/psoc
PSoC 1 | PSoC 3 | PSoC 4 | PSoC 5LP

Cypress Developer Community

[Community](#) | [Forums](#) | [Blogs](#) | [Video](#) | [Training](#)

Technical Support

cypress.com/support

© Cypress Semiconductor Corporation, 2015-2016. The information contained herein is subject to change without notice. Cypress Semiconductor Corporation assumes no responsibility for the use of any circuitry other than circuitry embodied in a Cypress product. Nor does it convey or imply any license under patent or other rights. Cypress products are not warranted nor intended to be used for medical, life support, life saving, critical control or safety applications, unless pursuant to an express written agreement with Cypress. Furthermore, Cypress does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress products in life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress against all charges.

Any Source Code (software and/or firmware) is owned by Cypress Semiconductor Corporation (Cypress) and is protected by and subject to worldwide patent protection (United States and foreign), United States copyright laws and international treaty provisions. Cypress hereby grants to licensee a personal, non-exclusive, non-transferable license to copy, use, modify, create derivative works of, and compile the Cypress Source Code and derivative works for the sole purpose of creating custom software and or firmware in support of licensee product to be used only in conjunction with a Cypress integrated circuit as specified in the applicable agreement. Any reproduction, modification, translation, compilation, or representation of this Source Code except as specified above is prohibited without the express written permission of Cypress.

Disclaimer: CYPRESS MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARD TO THIS MATERIAL, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE. Cypress reserves the right to make changes without further notice to the materials described herein. Cypress does not assume any liability arising out of the application or use of any product or circuit described herein. Cypress does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress' product in a life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress against all charges.

Use may be limited by and subject to the applicable Cypress software license agreement.